



Materials Declaration Form

IPC	1752	Version	2
Form Type *	Distribute		
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

*** : Required Field**

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2020-05-04
Company Unique ID	NL 008751171B01		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacobello	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STO36N60M6	CS9X*BQ6KB8L	A	996I	2020-05-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	692	mg	Each	ECOPACK® 2
Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	DM00542669	

Package Designator	Size	Nbr of instances	Shape	
SIP	9.9 -11.68-2.3	8	flat	
Comment	TO-LL			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.91	die	1314
Lead	3.36	soft solder	4860

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	3.36	Soft solder	4860
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	3.363	Soft solder	924917

Material Composition Declaration :						Mfr Item Name	CS9X*BQ6KB8L					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	15.196	mg	supplier	die	Silicon(Si)	7440-21-3		13.598	mg	894841	19650
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.355	mg	23361	513
				supplier	metallisation	Copper(Cu)	7440-50-8		0.131	mg	8621	189
				supplier	metallisation	Nickel(Ni)	7440-02-0		0.909	mg	59818	1314
				supplier	metallisation	Silver(Ag)	7440-22-4		0.092	mg	6054	133
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.022	mg	1448	33
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.082	mg	5396	118
Leadframe	M-004 Copper and its alloys	312.572	mg	supplier	passivation	Silicon oxide	7631-86-9		0.007	mg	461	10
				supplier	alloy & coating	Copper(Cu)	7440-50-8		312.165	mg	998698	451105
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.313	mg	1001	452
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.094	mg	301	136
Soft solder	Solder	3.636	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	3.363	mg	924917	4860
				supplier	solder	Tin(Sn)	7440-31-5		0.182	mg	50055	263
				supplier	solder	Silver(Ag)	7440-22-4		0.091	mg	25028	132
Bonding wires	M-004 Copper and its alloys	1.499	mg	supplier	wire	Copper (Cu)	7440-50-8		1.499	mg	1000000	2166
Encapsulation	M-011 Other inorganic materials	357.198	mg	supplier	mold compound	Silica	60676-86-0		326.836	mg	915000	472306
				supplier	mold compound	Epoxy Resin	25068-38-6		21.432	mg	60000	30971
				supplier	mold compound	Phenolic Resin	29690-82-2		7.144	mg	20000	10324
				supplier	mold compound	Carbon Black	1333-86-4		1.786	mg	5000	2581
connections coating	Solder	1.899	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.899	mg	1000000	2744